Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	5
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	82.0	6.59 E-03	384577
Resin	15.0	1.20 E-03	70264
Sb2O3	1.4	1.12 E-04	6558
Brominated epoxy	1.0	8.03 E-05	4684
Carbon Black	0.6	4.02 E-05	2342
Subtotal		8.03 E-03	468425

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.95 E-03	405685
Fe	2.35	1.62 E-04	9475
Zn	0.12	9.00 E-06	525
P	0.03	1.73 E-06	101
Subtotal		7.13 E-03	415786

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	7.20 E-05	4200

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	6.93 E-04	40422

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.50 E-04	8749

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.00 E-03	58334

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	5.60 E-05	3267
Resin	15	1.05 E-05	613
Aromatic Amine	5	3.50 E-06	204
Subtotal		7.00 E-05	4083

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3052. ICP-AES.
Cd	Not Detected	EPA Method 3052. ICP-AES.
Hg	Not Detected	EPA Method 3052. ICP-AES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Package Totals

Weight (g)	PPM
1.71 E-02	1000000

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ADI Proprietary

Materials Declaration

Package	SOT23-COL
Body Size	
LeadCount	5
Option	NiPdAu

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	80.8	6.49 E-03	394428
Epoxy resin	9.0	7.23 E-04	43934
Phenol Resin	5.0	4.02 E-04	24408
Metal Hydroxide	5.0	4.02 E-04	24408
Carbon Black	0.2	1.61 E-05	976
Subtotal	100.0	8.03 E-03	488153

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	6.94 E-03	421619
Iron	2.35	1.62 E-04	9874
Zinc	0.12	9.00 E-06	547
Phosphorus	0.03	1.73 E-06	105
Subtotal	100	7.11 E-03	432146

Internal/External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Nickel	90.91	8.28 E-05	5034
Palladium	7.91	7.20 E-06	438
Gold	1.19	1.08 E-06	66
Subtotal	100.00	9.11 E-05	5537

Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	1.50 E-04	9118

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	1.00 E-03	60791

Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	2.17 E-05	1319
Metal Oxide	31	2.17 E-05	1319
Glycol Ethers	22	1.54 E-05	936
Silica	8	5.60 E-06	340
Curing agent & hardener	8	5.60 E-06	340
Subtotal	100	7.00 E-05	4255

Molding Compound

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES
Cadmium	Not Detected	Draft IEC 62321. ICP-OES
Mercury	Not Detected	Draft IEC 62321. ICP-OES
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Die Attach Paste

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES
Cadmium	Not Detected	Draft IEC 62321. ICP-OES
Mercury	Not Detected	Draft IEC 62321. ICP-OES
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
1.64 E-02	1000000

RJ-03

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Materials Declaration

Package	SOT 23
Body Size	--
LeadCount	5
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	82.0	6.59 E-03	383524
Resin	15.0	1.20 E-03	70071
Sb2O3	1.4	1.12 E-04	6540
Brominated epoxy	1.0	8.03 E-05	4671
Carbon Black	0.6	4.02 E-05	2336
Subtotal		8.03 E-03	467142

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.95 E-03	404574
Fe	2.35	1.62 E-04	9449
Zn	0.12	9.00 E-06	524
P	0.03	1.73 E-06	101
Subtotal		7.13 E-03	414648

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	7.20 E-05	4189

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	6.29 E-04	36592
Pb	15	1.11 E-04	6457
Subtotal		7.40 E-04	43049

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.50 E-04	8725

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.00 E-03	58175

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	5.60 E-05	3258
Resin	15	1.05 E-05	611
Aromatic Amine	5	3.50 E-06	204
Subtotal		7.00 E-05	4072

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3052. ICP-AES.
Cd	Not Detected	EPA Method 3052. ICP-AES.
Hg	Not Detected	EPA Method 3052. ICP-AES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Package Totals

Weight (g)	PPM
1.72 E-02	1000000

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